

Practitioner's Docket No. 704-010563-US(PAR)

CHAPTER II

09/936951

Preliminary Classification:

Proposed Class:

Subclass:

NOTE: "All applicants are requested to include a preliminary classification on newly filed patent applications. The preliminary classification, preferably class and subclass designations, should be identified in the upper right-hand corner of the letter of transmittal accompanying the application papers, for example 'Proposed Class 2, subclass 129.'" M.P.E.P., § 601, 7th ed.

**TRANSMITTAL LETTER
TO THE UNITED STATES ELECTED OFFICE (EO/US)
(ENTRY INTO U.S. NATIONAL PHASE UNDER CHAPTER II)**

INTERNATIONAL APPLICATION NO.	INTERNATIONAL FILING DATE	PRIORITY DATE CLAIMED
PCT/EP00/02747	March 2, 2000	March 16, 1999
TITLE OF INVENTION		
MODULAR OPTOELECTRONIC CONNECTOR		
APPLICANT(S)		
Bernard ROBERT, Mostafa El ZINDINE , Bernard BRICE		

Box PCT
Assistant Commissioner for Patents
Washington D.C. 20231
ATTENTION: EO/US

CERTIFICATION UNDER 37 C.F.R. §§ 1.8(a) and 1.10*
(When using Express Mail, the Express Mail label number is mandatory;
Express Mail certification is optional.)

I hereby certify that, on the date shown below, this correspondence is being:

MAILING

☒ deposited with the United States Postal Service in an envelope addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231

37 C.F.R. § 1.8(a)

37 C.F.R. § 1.10 *

☐ with sufficient postage as first class mail.

☒ as "Express Mail Post Office to Addressee"

Mailing Label No. EL627426938IJS (mandatory)**TRANSMISSION**

☐ facsimile transmitted to the Patent and Trademark Office, (703) _____

Signature

Deborah J. Clark

(type or print name of person certifying)

Date: September 17, 2001

* Only the date of filing (§ 1.6) will be the date used in a patent term adjustment calculation, although the date on any certificate of mailing or transmission under § 1.8 continues to be taken into account in determining timeliness. See § 1.703(f). Consider "Express Mail Post Office to Addressee" (§ 1.10) or facsimile transmission (§ 1.6(d)) for the reply to be accorded the earliest possible filing date for patent term adjustment calculations.

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NOTE: To avoid abandonment of the application, the applicant shall furnish to the USPTO, not later than 20 months from the priority date: (1) a copy of the international application, unless it has been previously communicated by the International Bureau or unless it was originally filed in the USPTO; and (2) the basic national fee (see 37 C.F.R. § 1.492(a)). The 30-month time limit may not be extended. 37 C.F.R. § 1.495.

WARNING: Where the items are those which can be submitted to complete the entry of the international application into the national phase are subsequent to 30 months from the priority date the application is still considered to be in the international state and if mailing procedures are utilized to obtain a date the express mail procedure of 37 C.F.R. § 1.10 must be used (since international application papers are not covered by an ordinary certificate of mailing—See 37 C.F.R. § 1.8.

NOTE: Documents and fees must be clearly identified as a submission to enter the national state under 35 U.S.C. § 371 otherwise the submission will be considered as being made under 35 U.S.C. § 111. 37 C.F.R. § 1.494(f).

- I. Applicant herewith submits to the United States Elected Office (EO/US) the following items under 35 U.S.C. § 371:
- a. ☒ This express request to immediately begin national examination procedures (35 U.S.C. § 371(f)).
 - b. ☒ The U.S. National Fee (35 U.S.C. § 371(c)(1)) and other fees (37 C.F.R. § 1.492) as indicated below:

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2. Fees

CLAIMS FEE	(1) FOR	(2) NUMBER FILED	(3) NUMBER EXTRA	(4) RATE	(5) CALCULATIONS
<input type="checkbox"/> *	TOTAL CLAIMS				
	18	18 - 20 =	0	× \$18.00 =	\$ 0
	INDEPENDENT CLAIMS				
	2	2 - 3 =	0	× \$80.00 =	0
	MULTIPLE DEPENDENT CLAIM(S) (if applicable) + \$270.00				
BASIC FEE**	<input type="checkbox"/> U.S. PTO WAS INTERNATIONAL PRELIMINARY EXAMINATION AUTHORITY Where an International preliminary examination fee as set forth in § 1.482 has been paid on the international application to the U.S. PTO: <input type="checkbox"/> and the international preliminary examination report states that the criteria of novelty, inventive step (non-obviousness) and industrial activity, as defined in PCT Article 33(1) to (4) have been satisfied for all the claims presented in the application entering the national stage (37 C.F.R. § 1.492(a)(4)) \$100.00 <input type="checkbox"/> and the above requirements are not met (37 C.F.R. § 1.492(a)(1)) \$690.00 <input checked="" type="checkbox"/> U.S. PTO WAS NOT INTERNATIONAL PRELIMINARY EXAMINATION AUTHORITY Where no international preliminary examination fee as set forth in § 1.482 has been paid to the U.S. PTO, and payment of an international search fee as set forth in § 1.445(a)(2) to the U.S. PTO: <input type="checkbox"/> has been paid (37 C.F.R. § 1.492(a)(2)) \$710.00 <input type="checkbox"/> has not been paid (37 C.F.R. § 1.492(a)(3)) \$1000.00 <input checked="" type="checkbox"/> where a search report on the international application has been prepared by the European Patent Office or the Japanese Patent Office (37 C.F.R. § 1.492(a)(5)) \$860.00				860.00
	Total of above Calculations =				860.00
SMALL ENTITY	Reduction by 1/2 for filing by small entity, if applicable. Assertion must be made. (note 37 C.F.R. § 1.27)				-
	Subtotal				
	Total National Fee \$				860.00
	Fee for recording the enclosed assignment document \$40.00 (37 C.F.R. § 1.21(h)). (See Item 13 below). See attached "ASSIGNMENT COVER SHEET".				
TOTAL	Total Fees enclosed \$				860.00

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*See attached Preliminary Amendment Reducing the Number of Claims.

- ☒ Attached is a ☒ check ☐ money order in the amount of \$ 860.00
- ☐ Authorization is hereby made to charge the amount of \$ _____
- ☒ to Deposit Account No. 16-1350
- ☐ to Credit card as shown on the attached credit card information authorization form PTO-2038.

WARNING: Credit card information should **not** be included on this form as it may become public.

- ☒ Charge any additional fees required by this paper or credit any overpayment in the manner authorized above.

A duplicate of this paper is attached.

****WARNING:** "To avoid abandonment of the application the applicant shall furnish to the United States Patent and Trademark Office not later than the expiration of 30 months from the priority date: * * * (2) the basic national fee (see § 1.492(a)). The 30-month time limit may not be extended." 37 C.F.R. § 1.495(b).

WARNING: If the translation of the international application and/or the oath or declaration have not been submitted by the applicant within thirty (30) months from the priority date, such requirements may be met within a time period set by the Office. 37 C.F.R. § 1.495(b)(2). The payment of the surcharge set forth in § 1.492(e) is required as a condition for accepting the oath or declaration later than thirty (30) months after the priority date. The payment of the processing fee set forth in § 1.492(f) is required for acceptance of an English translation later than thirty (30) months after the priority date. Failure to comply with these requirements will result in abandonment of the application. The provisions of § 1.136 apply to the period which is set. Notice of Jan. 3, 1993, 1147 O.G. 29 to 40.

- ☐ **Assertion of Small Entity Status**
- ☐ **Applicant hereby asserts status as a small entity under 37 C.F.R. § 1.27.**

NOTE: 37 C.F.R. § 1.27(c) deals with the assertion of small entity status, whether by a written specific declaration thereof or by payment as a small entity of the basic filing fee or the fee for the entry into the national phase as states:

"(c) Assertion of small entity status. Any party (person, small business concern or nonprofit organization) should make a determination, pursuant to paragraph (f) of this section, of entitlement to be accorded small entity status based on the definitions set forth in paragraph (a) of this section, and must, in order to establish small entity status for the purpose of paying small entity fees, actually make an assertion of entitlement to small entity status, in the manner set forth in paragraphs (c)(1) or (c)(3) of this section, in the application or patent in which such small entity fees are to be paid.

(1) Assertion by writing. Small entity status may be established by a written assertion of entitlement to small entity status. A written assertion must:

- (i) Be clearly identifiable;
- (ii) Be signed (see paragraph (c)(2) of this section); and

(iii) Convey the concept of entitlement to small entity status, such as by stating that applicant is a small entity, or that small entity status is entitled to be asserted for the application or patent. While no specific words or wording are required to assert small entity status, the intent to assert small entity status must be clearly indicated in order to comply with the assertion requirement.

(2) Parties who can sign and file the written assertion. The written assertion can be signed by:

- (i) One of the parties identified in §§ 1.33(b) (e.g., an attorney or agent registered with the Office), §§ 3.73(b) of this chapter notwithstanding, who can also file the written assertion;
- (ii) At least one of the individuals identified as an inventor (even though a §§ 1.63 executed oath or declaration has not been submitted), notwithstanding §§ 1.33(b)(4), who can also file the written assertion pursuant to the exception under §§ 1.33(b) of this part; or
- (iii) An assignee of an undivided part interest, notwithstanding §§ 1.33(b)(3) and 3.73(b) of this chapter, but the partial assignee cannot file the assertion without resort to a party identified under §§ 1.33(b) of this part.

(3) Assertion by payment of the small entity basic filing or basic national fee. The payment, by any party, of the exact amount of one of the small entity basic filing fees set forth in §§ 1.16(a), (f), (g), (h), or (k), or one of the small entity basic national fees set forth in §§ 1.492(a)(1), (a)(2), (a)(3), (a)(4), or (a)(5), will be treated as a written assertion of entitlement to small entity status even if the type of basic filing or basic national fee is inadvertently selected in error.

(i) If the Office accords small entity status based on payment of a small entity basic filing or basic national fee under paragraph (c)(3) of this section that is not applicable to that application, any balance of the small entity fee that is applicable to that application will be due along with the appropriate surcharge set forth in §§ 1.16(e), or §§ 1.16(f).

(ii) The payment of any small entity fee other than those set forth in paragraph (c)(3) of this section (whether in the exact fee amount or not) will not be treated as a written assertion of entitlement to small entity status and will not be sufficient to establish small entity status in an application or a patent."

3. ☒ A copy of the International application as filed (35 U.S.C. § 371(c)(2)):

NOTE: Section 1.495 (b) was amended to require that the basic national fee and a copy of the international application must be filed with the Office by 30 months from the priority date to avoid abandonment. "The International Bureau normally provides the copy of the international application to the Office in accordance with PCT Article 20. At the same time, the International Bureau notifies applicant of the communication to the Office. In accordance with PCT Rule 47.1, that notice shall be accepted by all designated offices as conclusive evidence that the communication has duly taken place. Thus, if the applicant desires to enter the national stage, the applicant normally need only check to be sure the notice from the International Bureau has been received and then pay the basic national fee by 30 months from the priority date." Notice of Jan. 7, 1993, 1147 O.G. 29 to 40, at 35-36. See item 14c below.

- a. ☐ is transmitted herewith.
- b. ☐ is not required, as the application was filed with the United States Receiving Office.
- c. ☒ has been transmitted
 - i. ☒ by the International Bureau.

Date of mailing of the application (from form PCT/1B/308):
9/21/00

- ii. ☐ by applicant on _____. (Date)

4. ☐ A translation of the International application into the English language (35 U.S.C. § 371(c)(2)):

- a. ☐ is transmitted herewith.
- b. ☐ is not required as the application was filed in English.
- c. ☐ was previously transmitted by applicant on _____. (Date)
- d. ☐ will follow.

5. ☒ Amendments to the claims of the International application under PCT Article 19 (35 U.S.C. § 371(c)(3)):

NOTE: The Notice of January 7, 1993 points out that 37 C.F.R. § 1.495(a) was amended to clarify the existing and continuing practice that PCT Article 19 amendments must be submitted by 30 months from the priority date and this deadline may not be extended. The Notice further advises that: "The failure to do so will not result in loss of the subject matter of the PCT Article 19 amendments. Applicant may submit that subject matter in a preliminary amendment filed under section 1.121. In many cases, filing an amendment under section 1.121 is preferable since grammatical or idiomatic errors may be corrected." 1147 O.G. 29-40, at 36.

- a. ☐ are transmitted herewith.
 b. ☐ have been transmitted
 i. ☐ by the International Bureau.

Date of mailing of the amendment (from form PCT/1B/308):

- ii. ☐ by applicant on _____ (Date)

- c. ☒ have not been transmitted as

- i. ☒ applicant chose not to make amendments under PCT Article 19.
 Date of mailing of Search Report (from form PCT/ISA/210.):

9/26/00

- ii. ☐ the time limit for the submission of amendments has not yet expired. The amendments or a statement that amendments have not been made will be transmitted before the expiration of the time limit under PCT Rule 46.1.

6. ☒ A translation of the amendments to the claims under PCT Article 19 (38 U.S.C. § 371(c)(3)):

- a. ☐ is transmitted herewith.
 b. ☐ is not required as the amendments were made in the English language.
 c. ☒ has not been transmitted for reasons indicated at point 5(c) above.

7. ☒ A copy of the international examination report (PCT/IPEA/409)

☒ is transmitted herewith.

☐ is not required as the application was filed with the United States Receiving Office.

8. ☒ Annex(es) to the international preliminary examination report

- a. ☒ is/are transmitted herewith.
 b. ☐ is/are not required as the application was filed with the United States Receiving Office.

9. ☒ A translation of the annexes to the international preliminary examination report

- a. ☐ is transmitted herewith.
 b. ☒ is not required as the annexes are in the English language.

(Transmittal Letter to the United States Elected Office (EO/US) [13-18]—page 6 of 9)

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10. ☒ An oath or declaration of the inventor (35 U.S.C. § 371(c)(4)) complying with 35 U.S.C. § 115
- a. ☐ was previously submitted by applicant on _____. (Date)
 - b. ☐ is submitted herewith, and such oath or declaration
 - i. ☐ is attached to the application.
 - ii. ☐ identifies the application and any amendments under PCT Article 19 that were transmitted as stated in points 3(b) or 3(c) and 5(b); and states that they were reviewed by the inventor as required by 37 C.F.R. § 1.70.
 - c. ☒ will follow.

II. Other document(s) or information included:

11. ☒ An International Search Report (PCT/ISA/210) or Declaration under PCT Article 17(2)(a):
- a. ☒ is transmitted herewith.
 - b. ☐ has been transmitted by the International Bureau.
Date of mailing (from form PCT/IB/308): _____
 - c. ☐ is not required, as the application was searched by the United States International Searching Authority.
 - d. ☐ will be transmitted promptly upon request.
 - e. ☐ has been submitted by applicant on _____. (Date)
12. ☒ An Information Disclosure Statement under 37 C.F.R. §§ 1.97 and 1.98:
- a. ☐ is transmitted herewith.

Also transmitted herewith is/are:

- ☐ Form PTO-1449 (PTO/SB/08A and 08B).
 - ☐ Copies of citations listed.
 - b. ☒ will be transmitted within THREE MONTHS of the date of submission of requirements under 35 U.S.C. § 371(c).
 - c. ☐ was previously submitted by applicant on _____. (Date)
13. ☐ An assignment document is transmitted herewith for recording.
- A separate ☐ "COVER SHEET FOR ASSIGNMENT (DOCUMENT) ACCOMPANYING NEW PATENT APPLICATION" or ☐ FORM PTO 1595 is also attached.

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14. ☒ Additional documents:

- a. ☒ Copy of request (PCT/RO/101)
- b. ☒ International Publication No. WO 00/55665
 - i. ☒ Specification, claims and drawing
 - ii. ☐ Front page only
- c. ☒ Preliminary amendment (37 C.F.R. § 1.121)
- d. ☒ Other
PCT/IB/308 Written Opinion, Observations and claims in response to written opinion

15. ☒ The above checked items are being transmitted

- a. ☒ before 30 months from any claimed priority date.
- b. ☐ after 30 months.

16. ☐ Certain requirements under 35 U.S.C. § 371 were previously submitted by the applicant on _____, namely:

AUTHORIZATION TO CHARGE ADDITIONAL FEES

WARNING: Accurately count claims, especially multiple dependant claims, to avoid unexpected high charges if extra claims are authorized.

NOTE: "A written request may be submitted in an application that is an authorization to treat any concurrent or future reply, requiring a petition for an extension of time under this paragraph for its timely submission, as incorporating a petition for extension of time for the appropriate length of time. An authorization to charge all required fees, fees under § 1.17, or all required extension of time fees will be treated as a constructive petition for an extension of time in any concurrent or future reply requiring a petition for an extension of time under this paragraph for its timely submission. Submission of the fee set forth in § 1.17(a) will also be treated as a constructive petition for an extension of time in any concurrent reply requiring a petition for an extension of time under this paragraph for its timely submission." 37 C.F.R. § 1.136(a)(3).

NOTE: "Amounts of twenty-five dollars or less will not be returned unless specifically requested within a reasonable time, nor will the payer be notified of such amounts; amounts over twenty-five dollars may be returned by check or, if requested, by credit to a deposit account." 37 C.F.R. § 1.26(a).

☒ Please charge, in the manner authorized above, the following additional fees that may be required by this paper and during the entire pendency of this application:

☒ 37 C.F.R. § 1.492(a)(1), (2), (3), and (4) (filing fees)

WARNING: Because failure to pay the national fee within 30 months without extension (37 C.F.R. § 1.495(b)(2)) results in abandonment of the application, it would be best to always check the above box.

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17 SEP 2001

☒ 37 C.F.R. § 1.492(b), (c) and (d) (presentation of extra claims)

NOTE: Because additional fees for excess or multiple dependent claims not paid on filing or on later presentation must only be paid or these claims cancelled by amendment prior to the expiration of the time period set for response by the PTO in any notice of fee deficiency (37 C.F.R. § 1.492(d)), it might be best not to authorize the PTO to charge additional claim fees, except possible when dealing with amendments after final action.

☒ 37 C.F.R. § 1.17 (application processing fees)

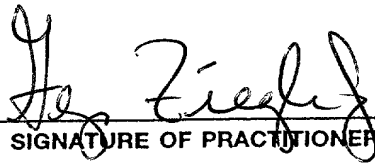
☒ 37 C.F.R. § 1.17(a)(1)-(5) (extension fees pursuant to § 1.136(a).

☐ 37 C.F.R. § 1.18 (issue fee at or before mailing of Notice of Allowance, pursuant to 37 C.F.R. § 1.311(b))

NOTE: Where an authorization to charge the issue fee to a deposit account has been filed before the mailing of a Notice of Allowance, the issue fee will be automatically charged to the deposit account at the time of mailing the notice of allowance. 37 C.F.R. § 1.311(b).

NOTE: 37 C.F.R. § 1.28(b) requires "Notification of any change in loss of entitlement to small entity status must be filed in the application . . . prior to paying, or at the time of paying . . . issue fee." From the wording of 37 C.F.R. § 1.28(b): (a) notification of change of status must be made even if the fee is paid as "other than a small entity" and (b) no notification is required if the change is to another small entity.

☒ 37 C.F.R. § 1.492(e) and (f) (surcharge fees for filing the declaration and/or filing an English translation of an International Application later than 30 months after the priority date).



SIGNATURE OF PRACTITIONER

Reg. No.: 44,004

Geza C. Ziegler, Jr.

Tel. No.: (203) 259-1800

(type or print name of practitioner)

PERMAN & GREEN, LLP

Customer No.: 2512

P.O. Address

425 Post Road, Fairfield, CT 06430 USA

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JC03 Rec'd PCT/PTO

17 SEP 2001

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Express Mail No.: EL627426938US

In re Application of: ROBERT et al.

INTERNATIONAL APPLICATION NO.: PCT/EP00/02747

INTERNATIONAL FILING DATE: 3/2/00

TITLE: MODULAR OPTOELECTRONIC CONNECTOR

ATTORNEY DOCKET NO.: 704-010563-US (PAR)

Box PCT

Commissioner of Patents

Washington, D.C. 20231

PRELIMINARY AMENDMENT

Dear Sir:

Please amend the above-identified, patent application as follows:

IN THE SPECIFICATION:

After the Title and before the first paragraph, please insert the following paragraph:

This application claims the benefit of the earlier filed International Application No. PCT/EP00/02747, International Filing Date, March 2, 2000, which designated the United States of America, and which International application was published under PCT Article 21(2) in English as WO Publication No. WO 00/55665.

IN THE CLAIMS

PLEASE CANCEL CLAIMS 1-14 without prejudice.

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IN THE SECTION MARKED "CLAIMS" PLEASE ADD THE
FOLLOWING NEW TEXT AND CLAIMS 15 THROUGH 32 AS WRITTEN
BELOW:

CLAIMS

What is claimed is:

15. Optoelectronic connector comprising a package (1), an optical port (2), an electrical port (3), an optoelectronic circuit positioned in this package and connected to these two ports, the optoelectronic circuit comprising a bare control (5-7) and emission-detection (8) integrated circuit chip, an internal wall (29) of the package being provided with metallized connections (11), pads (10) of this integrated circuit being connected (12) directly to the metallized connections, characterized in that it comprises laser diodes (8), said laser diodes being firstly laid out on a gallium arsenide substrate (43), then deposited on an intermediate support (45), this support being turned over in order to transfer the laser diodes on the integrated circuit, this connector constituting a basic unit link.

16. Connector according to claim 15, characterized in that the laser diodes (8) are transferred (45) on the integrated circuit with a space (50) between these diodes equal to a space (21) between optical fiber terminations in the optical port.

17. Connector according to claim 15, characterized in that the package is an MID type package with connection metallizations deposited in a cavity of this package, contact armorings of

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the electrical port of this connector being formed by one of these metallizations.

18. Connector according to claim 17, characterized in that the MID type package is made by means of a method with metallizations in two passes.

19. Connector according to claim 17, characterized in that the package is connected to the integrated circuit by BGA type connections, wire bonding or anisotropic film technology.

20. Connector according to claim 17, characterized in that the shielding of the package is of an MID type.

21. Connector according to claim 15, characterized in that pads (10) of the integrated circuit are connected (12) directly to the metallized connections.

22. Connector according to claim 15, characterized in that the laser diodes are VCSEL diodes, preferably of the GaAs type.

23. Connector according to claim 15, characterized in that the optical port comprises an inclined mirror (19), preferably inclined at 45°.

24. Connector according to claim 15, characterized in that the optical port comprises a part (18) for positioning optical fiber terminations, this part abutting (23) a cant (24) of the integrated circuit.

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General Information	
Item	Value
NAME	John Doe
AGE	35
SEX	Male
HEIGHT	175 cm
WEIGHT	70 kg
DATE OF BIRTH	1988-01-15
Medical History	
Current Medications	Aspirin, Metoprolol
Previous Surgeries	Appendectomy, Hip Replacement
Chronic Conditions	Hypertension, Diabetes
Vital Signs	
BP	120/80 mmHg
HR	72 bpm
RR	18 bpm
Temp	37.2°C
Laboratory Results	
Hemoglobin	14.5 g/dL
Hematocrit	42.5%
Platelets	150,000/mm³
Glucose	100 mg/dL
Cholesterol	180 mg/dL
Urea Nitrogen	10 mg/dL
Creatinine	1.2 mg/dL
Immunization Status	
MMR	Up to date
Tdap	Up to date
Flu	Up to date
COVID-19	Up to date
Allergies	
Food	None
Medication	Penicillin
Latex	None
Social History	
Smoking	Former smoker
Alcohol	Occasional
Exercise	Regular
Occupation	Software Engineer
Family History	Heart Disease, Cancer
Patient Signature	
Signature	[Signature]
Date	2023-10-27

General Information	
Item	Value
1. Name of the project	Project X
2. Date of completion	12/31/2023
3. Location	New York, NY
4. Client Name	ABC Corporation
5. Project Manager	John Doe
6. Budget	\$1,000,000
7. Status	Completed
8. Description	Development of a new software application for internal use.
9. Objectives	Improve efficiency, reduce costs, and enhance user experience.
10. Key Deliverables	Software application, User manual, Training materials.
11. Risks	Scope creep, Budget overruns, Delays.
12. Mitigation Strategies	Regular communication, Strict budget control, Flexible scheduling.
13. Conclusion	The project was successfully completed within the budget and timeline.
14. Recommendations	Implement the software application and monitor its performance.
15. Signatures	Project Manager: John Doe, Client: ABC Corporation.

General Information	
Item	Value
NAME	John Doe
AGE	35
SEX	Male
HEIGHT	175 cm
WEIGHT	70 kg
DATE OF BIRTH	1988-01-15
Medical History	
Current Conditions	None
Previous Conditions	None
Medications	None
Family History	None
Vital Signs	
BP	120/80 mmHg
HR	75 bpm
RR	18 bpm
SpO2	98%
Temp	37.2°C
Physical Examination	
General	Well
HEENT	Normal
CV	Normal
Respiratory	Normal
GI	Normal
GU	Normal
Neuro	Normal
Laboratory Tests	
Complete Blood Count	Normal
Uric Acid	4.5 mg/dL
Urea Nitrogen	10 mg/dL
Creatinine	1.2 mg/dL
Glucose	100 mg/dL
Lipid Panel	Normal
Imaging Studies	
X-ray	Normal
Ultrasound	Normal
CT Scan	Normal
MRI	Normal
Treatment Plan	
Medications	None
Procedures	None
Follow-up	6 weeks

General Information	
Item	Value
NAME	John Doe
AGE	35
SEX	Male
HEIGHT	175 cm
WEIGHT	70 kg
DATE OF BIRTH	1988-01-15
Medical History	
Current Conditions	None
Previous Conditions	None
Medications	None
Family History	None
Vital Signs	
BP	120/80 mmHg
HR	75 bpm
RR	18 bpm
SpO2	98%
Temp	37.2°C
Physical Examination	
General	Well
HEENT	Normal
CV	Normal
Respiratory	Normal
GI	Normal
GU	Normal
Neuro	Normal
Laboratory Tests	
Complete Blood Count	Normal
Uric Acid	4.5 mg/dL
Urea Nitrogen	10 mg/dL
Creatinine	1.2 mg/dL
Glucose	100 mg/dL
Lipid Panel	Normal
Imaging Studies	
X-ray	Normal
Ultrasound	Normal
CT Scan	Normal
MRI	Normal
Treatment Plan	
Medications	None
Procedures	None
Follow-up	6 weeks

General Information	
Variable	Value
Study ID	12345
Study Title	Investigation of the Effects of X on Y
Principal Investigator	Dr. John Doe
Study Period	January 2023 - December 2023
Study Location	University of Example
Study Design	Randomized Controlled Trial
Sample Size	100
Number of Groups	2
Group 1 (Control)	50
Group 2 (Intervention)	50
Intervention Description	Administration of X at a dose of 100mg daily for 12 weeks.
Control Description	Administration of a placebo (identical in appearance to X) at a dose of 100mg daily for 12 weeks.
Primary Outcome Measure	Change in Y (measured in units of Z) over 12 weeks.
Secondary Outcome Measures	Adverse effects, compliance, and quality of life.
Statistical Analysis	Two-sample t-test, ANOVA, and regression analysis.
Significance Level	0.05
Power	0.80
Confidence Interval	95%
Results Summary	Group 2 showed a significantly greater increase in Y compared to Group 1 (p < 0.05).
Conclusion	The intervention X appears to have a positive effect on Y.
Recommendations	Further research is needed to confirm these findings and explore the mechanism of action.
References	See attached list of references.
Appendices	See attached appendices for raw data and detailed statistical results.
Notes	None.

metallized connections, characterized in that it comprises following steps

- laser diodes (8) are laid out on a gallium arsenide substrate (43),
- they are deposited on an intermediate support (45),
- this intermediate support is turned over in order to face the integrated circuit, and then
- the laser diodes are transferred on this integrated circuit.

30. Method according to claim 29, characterized in that the intermediate support is a glass plate, and that

- said glass plate exists from the very time when laser diodes are laid out, and that
- the gallium arsenide substrate is etched in order to present the laser diodes over the glass plate.

31. Method according to claim 29, characterized in that laser diodes are deposited on the intermediate support with a spacing between each other equal to a space between two optical fibers (17-20) in the connector.

32. Method according to claim 29, characterized in that transfer of the laser diodes is done by laser insolation of the intermediate support.

1990-1991		1991-1992		1992-1993		1993-1994		1994-1995		1995-1996		1996-1997		1997-1998		1998-1999		1999-2000		2000-2001		2001-2002		2002-2003		2003-2004		2004-2005		2005-2006		2006-2007		2007-2008		2008-2009		2009-2010		2010-2011		2011-2012		2012-2013		2013-2014		2014-2015		2015-2016		2016-2017		2017-2018		2018-2019		2019-2020		2020-2021		2021-2022		2022-2023		2023-2024		2024-2025		2025-2026		2026-2027		2027-2028		2028-2029		2029-2030		2030-2031		2031-2032		2032-2033		2033-2034		2034-2035		2035-2036		2036-2037		2037-2038		2038-2039		2039-2040		2040-2041		2041-2042		2042-2043		2043-2044		2044-2045		2045-2046		2046-2047		2047-2048		2048-2049		2049-2050		2050-2051		2051-2052		2052-2053		2053-2054		2054-2055		2055-2056		2056-2057		2057-2058		2058-2059		2059-2060		2060-2061		2061-2062		2062-2063		2063-2064		2064-2065		2065-2066		2066-2067		2067-2068		2068-2069		2069-2070		2070-2071		2071-2072		2072-2073		2073-2074		2074-2075		2075-2076		2076-2077		2077-2078		2078-2079		2079-2080		2080-2081		2081-2082		2082-2083		2083-2084		2084-2085		2085-2086		2086-2087		2087-2088		2088-2089		2089-2090		2090-2091		2091-2092		2092-2093		2093-2094		2094-2095		2095-2096		2096-2097		2097-2098		2098-2099		2099-2100		2100-2101		2101-2102		2102-2103		2103-2104		2104-2105		2105-2106		2106-2107		2107-2108		2108-2109		2109-2110		2110-2111		2111-2112		2112-2113		2113-2114		2114-2115		2115-2116		2116-2117		2117-2118		2118-2119		2119-2120		2120-2121		2121-2122		2122-2123		2123-2124		2124-2125		2125-2126		2126-2127		2127-2128		2128-2129		2129-2130		2130-2131		2131-2132		2132-2133		2133-2134		2134-2135		2135-2136		2136-2137		2137-2138		2138-2139		2139-2140		2140-2141		2141-2142		2142-2143		2143-2144		2144-2145		2145-2146		2146-2147		2147-2148		2148-2149		2149-2150		2150-2151		2151-2152		2152-2153		2153-2154		2154-2155		2155-2156		2156-2157		2157-2158		2158-2159		2159-2160		2160-2161		2161-2162		2162-2163		2163-2164		2164-2165		2165-2166		2166-2167		2167-2168		2168-2169		2169-2170		2170-2171		2171-2172		2172-2173		2173-2174		2174-2175		2175-2176		2176-2177		2177-2178		2178-2179		2179-2180		2180-2181		2181-2182		2182-2183		2183-2184		2184-2185		2185-2186		2186-2187		2187-2188		2188-2189		2189-2190		2190-2191		2191-2192		2192-2193		2193-2194		2194-2195		2195-2196		2196-2197		2197-2198		2198-2199		2199-2200		2200-2201		2201-2202		2202-2203		2203-2204		2204-2205		2205-2206		2206-2207		2207-2208		2208-2209		2209-2210		2210-2211		2211-2212		2212-2213		2213-2214		2214-2215		2215-2216		2216-2217	
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REMARKS

After consideration of the documents cited in the International Search Report, and of the International Preliminary Examination Report, we have modified the set of claims as shown above. Modifications are supported by the description:

- claims 15 and 29 supported by page 10, lines 24-25, page 11, lines 19-20, and lines 24-26,
- claim 30 supported by page 11, lines 22-23,
- claim 31 supported by page 11, lines 21-22 and page 8, lines 28-29,
- claim 32 supported by page 11, lines 31-32

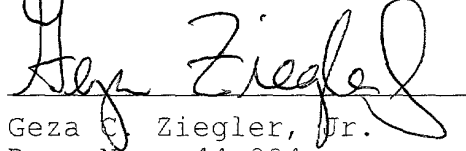
The claimed invention is protecting an optoelectronic connector comprising a package comprising an optical port, an electrical port, and a bare control and emission-detection integrated circuit chip. The integrated circuit chip is directly connected to metallized connections made in an internal wall of the package of the connector. More specifically the disclosed embodiment is an optoelectronic connector comprising laser diodes being transferred on the integrated circuit. The transfer of the diodes is made through at least two steps.

First diodes are laid out on an intermediate support, and then they are transferred on the integrated circuit. To be correctly disposed on the intermediate support, diodes may be firstly laid out on a gallium arsenide substrate.

They are then presented on the integrated circuit, and not on a substrate of printed circuit board type, neither on a connector's package type.

It is a feature of the disclosed embodiments to present a higher miniaturisation optoelectronic connector (Page 1, line 27, "With a view to miniaturisation"). The problem solved by the invention is clearly explained in the description (page 10, line 27-31 and page 11, lines 8-18).

Respectfully submitted,



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FOOTNOTES

MODULAR OPTOELECTRONIC CONNECTOR

An object of the present invention is a modular optoelectronic connector that can be used especially when high transmission bit rates are encountered. High bit rates of this kind are encountered for example in the field of telecommunications, especially for the interconnection of SDH type telephone exchanges. Each channel of an exchange of this kind must indeed give a bit rate of 622 Mbits. The expected developments are such that these bit rates must be raised to 2.5 Gbits and then 10 Gbits. High bit rates of this kind are furthermore being encountered in more limited spaces, as for example in computer local area networks or in aircraft. The bit rate requirements may then be also high owing to transmissions of image signals. Furthermore, inside one and the same piece of equipment, for example for the connection between several electronic racks in one and the same electronic cabinet, it may be planned to have very high bit rates.

To provide for the transmission of information of this kind without being hampered by problems of crosstalk or electromagnetic noise, it is preferred to use optical links. The invention pertains in fact to all optical links in which, ultimately, information has to be conveyed at a high information bit rate.

The preparation of information in electrical form and its transmission in optical form requires the making of optoelectronic couplers. In a first approach, devices have been developed in which an electronic card comprises an optoelectronic coupler of this kind. In this case, the electronic board can be accessed from outside by an optical connector. However, such an approach dictates the reservation of space on such an electronic board to make the electro-optical conversions. With a view to miniaturization, another approach is becoming prevalent. In this other approach, the coupler is an integral part of a connector. With this type of development, harnesses are appearing for example on the market. Harnesses of this kind comprise a cable and optoelectronic connectors at each of its ends. In a harness, the connectors are mounted on a cable. In the invention, it is thus planned, if necessary, to make harnesses of this kind. However, more generally in the invention, it is provided that the connectors may be distributed separately from the cables.

An optoelectronic connector according to the invention then comprises an electronic port linked to a coupler that is itself connected to an optical port. A cable to be connected to the optical port is an optical cable. At an another end of a link, a reverse conversion is done, and another connector is mounted. For the user, on either side of the cable, the links are electrical. The optoelectronic conversion is transparent to the user. The advantage of these approaches is of course a gain in space on the electrical cards which no longer has to incorporate a coupling function. Another advantage is simplicity of use. All that remains is a constraint relating to the electrical supply of the coupler but this is done through the electrical port.

An embodiment of this kind however has the drawback of being costly to manufacture. Indeed, the technologies implied in such a connector require strict compliance with various physical constraints. Thus, on the electrical port side, given the high information bit rates (for example in the range of several Gbits), it is necessary to act efficiently to counter radioelectrical noises. In the coupler, it is necessary to take account of the problems of thermal dissipation of the transducers used. Indeed, the known transducers, namely laser diodes, can consume up to 100 milliwatts per unit. The heat dissipation related to the working of the transducer prompts a heating of this transducer, resulting in a drift in its operating frequency.

Cost-related problems, for their part, lead to the making of multifiber sets. Indeed, since the mounting of a connector for a single optical fiber is costly, the cost is substantially reduced by providing for the connections of bundles of optical fibers. For example, there are known embodiments in which twenty optical fibers are connected to a connector. However, while an embodiment of this kind leads to a reduction in the cost price per optical fiber of the connector, it does not accurately correspond to requirements. With embodiments of this kind, the user may have access either to a connector with very many optical fibers or to a connector with a single optical fiber. However the cost is high in both cases. In the invention, optoelectronic links are sought wherein it is possible to make use of a modularity: the user, as required, can associate a desired number of optical fibers to meet his requirements.

The making of multifiber sets furthermore leads to specific difficulties. Indeed, owing to heat consumption, laser diodes have to be separated from

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one another by a substantial space inside the connector. Similarly, when the optoelectronic connector is mounted on an electronic card, the laser diodes are spaced out so that they can be mounted therein. Besides, in order to be able to get connected to this type of connector, it is necessary to get close to a termination of an optical fiber of the optical radiating element of the coupler. Now, the multifiber optical connectors have a standardized distribution of the optical terminations. In this standardized distribution, the terminations are close to each other. It is then necessary to create a waveguide in the optoelectronic connectors. This waveguide enables a geometrical matching between the necessarily big spacing between the laser diodes mounted in the optoelectronic connector and a close spacing close of the terminations of the optical fibers presented in a standardized optical connector. The making of a waveguide of this kind complicates the coupler. This waveguide itself must also comply with the above-mentioned constraints.

In practice, to make optoelectronic connectors of this kind, laser diodes using Vcsel technology are used. The term Vcsel refers to vertical cavity solid emitting lasers. With vertical cavity solid emitting lasers of this kind, the laser radiation is actually scattered in a scattering cone whose angular aperture is about 8° to 12° . It becomes easier to place an optical fiber termination in front of a cone of this kind to pick up the optical signal sent. However, the presence of the waveguide mentioned here above implies the making of two optical interfaces. A first interface is located between the laser diode and the input of the waveguide. A second interface is located at the output of the waveguide and at the input of the optical connector. These two interfaces lead to insertion losses which are themselves curbed by improving the quality of the optical terminations of the fibers of the optical connector and/or of the waveguides. For example, these ends of the fibers are polished by means of a plane or spherical polishing. If the polishing is plane, preferably it is slightly inclined with respect to the incident direction of the optical transmission so as not to prompt any parasitic reflections, both on the side of the interface with the laser diode and on the side of the interface with the optical connector. Ultimately, the presence of this waveguide results in a complex and costly structure if it is sought to prevent it from being a generator of transmission losses.

Furthermore, the electrical port that conveys the data elements must be especially well protected to prevent electromagnetic parasites. This shielding may be conventionally obtained by arrangements of metal partition walls. However, this type of approach is not compatible with desired goals of miniaturization and modularity of an optoelectronic connector. Or else, the manufacturing equipment becomes so precise that handling it runs counter to the conditions of very large-scale production.

In short, the approaches used for the prior art optoelectronic connectors are costly, not modular and do not have as good a transmission quality as would be desired.

It is an object of the invention to overcome these drawbacks by proposing an approach to the integration of the laser diodes into the optoelectronic connector that resolves all these problems simultaneously. According to a first embodiment of the invention, laser diodes are made by means of a weakly dissipative gallium arsenide (GaAs) technology. Using a thin layer transfer technique, these laser diodes are then placed directly on an integrated circuit comprising circuits for the driving, supply and amplification of the signals converted by the laser diodes. This direct transfer makes it possible to overcome the need for a printed circuit or a hybrid circuit which, in the prior art, enables the association of the laser diodes and the various electronic circuits needed to make them work.

This integrated circuit is itself directly placed in a package of the optoelectronic connector without being placed in an intermediate package that would contain it. Contact pads of this integrated circuit are connected to metallized zones made in a cavity of this package. Other pins of this integrated circuit are also connected to contact pads of one or more laser diodes transferred on this integrated circuit. These connections are made by wire bonding type microconnection techniques, ball grid array type or BGA type arrangements, or anisotropic type films. The package thus made is then sufficiently thin to be capable of being stacked at will and to enable the constitution of modular optoelectronic connectors with a number of electrical and/or optical ports that is determined at will.

Furthermore, the fact of transferring laser diodes, especially gallium arsenide laser diodes, on an integrated circuit that comprises all the functions needed for these diodes, enables them to be placed therein with a

mutual spacing such that it is equal to the spacing with which the terminations of the optical fibers are presented in the standardized optical connector. By acting in this way, direct compatibility is then achieved with a standardized distribution of an optical connector. Thus, it becomes unnecessary to interpose an optical waveguide between the optoelectronic coupler and the optical port. Consequently, insertion losses in the optical fibers are smaller. Consequently, the care taken in the making of the optical connectors becomes less important while at the same time providing for greater efficiency. Naturally, the cost of the connector is reduced owing to the absence of this interposed waveguide.

The solution to the problems of shielding is then preferably obtained by making a package of the connector by means of MID technology. With a technology of this kind, it is possible in one pass to metallize a part of a structure, a package, made of plastic or any other material. In the invention, in this structure, mechanical receptacles are made designed to receive male or female contacts of the electrical port. These receptacles have for example the shape of a cylindrical tube. Through their metallized back, they are connected to a contact that is introduced therein. Furthermore, the external surface of these tubes is metallized and this external metallization is connected to a ground contact. The external metallization is used as a shielding. If need be, the rest of the structure is molded on this assembly. By acting in this way, with metallizations made in one or two passes, the need for handling the partition walls is removed. The method can easily be adapted to large-scale manufacture because the structures are preferably molded.

An object of the invention therefore is an optoelectronic connector comprising a package, an optical port, an electrical port, an optoelectronic circuit positioned in this package and connected to these two ports, characterized in that the optoelectronic circuit comprises a bare control and emission-detection integrated circuit chip, an internal wall of the package being provided with metallized connections, pads of this integrated circuit being connected directly to the metallized connections, laser diodes being transferred on the integrated circuit.

This connector is thus constituting a basic unit link. By juxtaposing such basic unit links, it is possible to simply and efficiently make multiple-

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channel links. Thus, it is possible to set up a modular assembly of n links at very high bit rate or again a very high bit rate link obtained by the multiplexing of n links at a lower bit rate.

The invention will be understood more clearly from the following description and the appended figures, which are given purely by way of an indication and in no way restrict the scope of the invention. Of these figures:

- Figure 1 shows a view in perspective of an optoelectronic connector according to the invention;
- Figures 2a and 2b show two views (a top view and a front view) that are mutually perpendicular, of an optoelectronic connector module according to the invention;

- Figure 3 shows a schematic view in perspective of an embodiment of the package and of the electrical port of the connector of the invention;

- Figure 4 shows an embodiment of an integrated circuit that can be used in the connector of the invention.

Figure 1 shows a view in perspective of an optoelectronic connector according to the invention. This connector has a package 1, an optical port 2, and an electrical port 3. It also has an optoelectronic circuit 4 connected to these two ports. According to the invention, the optoelectronic circuit 4 is a control and transmission/detection integrated circuit chip, and the circuit 4 is bare, i.e. it is present in the package 1 without any conditioning package of its own. The circuit 4 is an integrated circuit having laser diodes and their controls. In one example, the integrated circuit 4 has supply circuits 5, driving circuits 6 and amplification and the shaping circuits 7 to control the laser diodes such as 8. The circuits 5, 6 and 7 are integrated on one and the same semiconductor substrate 9, for example conventionally made of silicon. In a preferred exemplary embodiment, the substrate 9 has a dimension of about 4 mm by 4 mm. The integrated circuit thus cleared is sufficient to contain all the circuits 5, 6 and 7 needed to drive two or four laser diodes such as 8. The integrated circuit 4 has connection pads 10 on its surface, in this case its upper surface. These pads 10 are directly connected to metallizations 11 of the package 1. These links can be made in various ways. In one example, the electrical links are wire bonding type links. This type of link is made by an automatic machine capable of feeding a very thin wire and of soldering one end of a section 12 of this wire to a pad 10 and another end to a

metallization 11 of the package. These machines are of a known type. The particular feature of the invention herein lies in the fact that the package of the optoelectronic connector 1 directly bears the metallizations 11 connected to the pad 10.

5 As shall be seen further below, the diodes such as 8 are not directly implanted in the integrated circuit but are preferably transferred therein. Indeed, the laser diodes used will preferably be gallium arsenide GaAs diodes. These diodes 8 also have connection pads 13. The pads 13 are connected by the same connection machine to pads 14 of the substrate of
10 the integrated circuit.

The technique of wire bonding is not the only technique possible. There is also the BGA technique in which solder balls are deposited on the pads such as 14 and 10 and are melted when they are put into contact with metallizations 11 or pads 13 of another circuit element. There also exists
15 another technology known as an anisotropic film connection technology. All these microscopic connection techniques can be used to make the connection of the integrated circuit 4 into the package 1 and the diodes 8 on the substrate of the circuit 4. In the example shown, the circuit 4 is for example bonded to the back of the package 1.

20 The package 1, in order that it may be very small, is a package of the type using metallizations. It is made for example by means of what is called a MID (molded interconnection device) technology. Without going into detail, for the implementation of a technique of this kind, a molded (plastic) shape is made having the requisite relief features and shapes. A selective chemical
25 etching operation is then carried out on a surface of the molded part with the activation of this surface, in particular with palladium. The selective etching is done for example after preliminary photomasking. The activation of the material of the package that results from this etching produces a locally distributed catalyst that efficiently receives a metallization layer. The
30 metallization layer obtained by the deposition of a metal adopts the geometry of the etching and enables the making of the metallized surfaces, such as the strip 11, with a desired shape. This operation can be done once with one pass. It is however possible to make a molding over the part thus metallized with another cover made of plastic for example and restart the metallization
35 operation. Thus, a metallized package is obtained in two passes. The value

of using a metallization in two passes makes it possible, as shall be seen further below, to make efficient electrical shieldings.

The package 1 also has the optical port 2. This optical port 2 essentially comprises a receptacle 15 to receive an optical connector 16, which is preferably a standardized optical connector. The receptacle 15 has walls that are used to guide and orient walls of the connector 16. Thus guided by these walls, optical terminations of optical fibers 17 of the connector 16 are presented to the light radiation emitted by the laser diodes 8. In the preferred exemplary embodiment, where the diodes 8 are transferred on the integrated circuit 4, they emit their light radiation in a direction substantially perpendicular to the surface of the integrated circuit 4. The optical port 2 then comprises for example a guiding part 18 provided with walls 15 and furthermore having an inclined face 19 in front of the optical terminations. The inclined face 19 is inclined in one example by 45° to the perpendicular to the plane of the integrated circuit 4 and with respect to the direction of insertion of the connector 16 into the port 2. This inclined face 19 is furthermore treated so that it is particularly reflective, for example by means of a layer of metal deposited on a plastic or silicon part 18. The inclined face 19 then reflects the radiation emitted by the laser diodes 8 towards the optical terminations of the optical fibers 17. The dismountable connector 16 can also be replaced by a non-dismountable positioning block. This non-dismountable block may consist of a precision molded plastic element (the molding provides for a precision of within one micrometer) or a silicon part with positioning Vee elements.

To provide for perfect securing of the guidance part 18 with respect to the diodes 8, the optoelectronic connector of the invention has two main characteristics. First of all, the diodes 8 are placed on the surface of the integrated circuit 4 with a space between them that is equal to a space 21 between two consecutive optical fibers 17 and 20 in the connector 16. The space 21 is thus the one that exists between a diode 8 and another diode 22 that is contiguous to it in the circuit 4. Furthermore, the part 18 has a securing edge 2 that is placed so that it abuts a cant 24 of the integrated circuit 4. By acting in this way, without any intermediate device, it is ensured that the optical terminations of the fibers 17 and 20 will be placed at the best position with respect to the transmission surfaces of the diodes 8 and 22.

It will be noted that it is possible to use an optical connector 16 of the type that is commercially available and use it to pick up the optical signal delivered by the diodes 8 and 22. All that is required is that the faces 15 of the optical port 2 should have dimensions corresponding to the type of optical connector 16 used. At least one of the faces of the optical port 2 will have a means of blocking the progress of the optical connector 16. For example, this can be obtained by a recess 25 in this face that is perpendicular to the direction of insertion of the optical connector 16 into the port 2.

Figure 1 shows the optoelectronic connector of the invention presented in the form of a module. Each module has a package 1 as well as a lid 26. The lid 26 is metallized at the appropriate places to contribute to the accurate shielding of the cavity of the package 1 in which the integrated circuit 4, the laser diodes and the various metallizations are located. For example, this lid may be metallized beneath its entire surface except at the position of the passage of the metallizations 11 above an upper shoulder of the cavity 29. The lid is thus of the MID type. In one very schematic example, the package 1 has relief features such as 27 and 28 to catch into an overall external structure that makes it possible to contain a certain number of them as required. As the case may be, the packages 1 and/or the lid 26 have raised relief parts (especially of the dovetailed type) used to associate two or more modules together.

Figures 2a and 2b repeat the elements of Figure 1 and give an even clearer view of the embodiment of the metallized package 1. At the back of a cavity 29 of this package 1, metallized pads 30 are placed connected to metallized connections 31 ending in the electrical port 3. In a preferred way, to facilitate modularity, the optoelectronic connector of the invention will be a connector with two, four or even eight optical channels. An optical channel can extend in an outgoing sense or in an incoming sense of the propagation of an optical signal or in a to-and-fro sense or again in a sense of optical propagation of a data signal and a sense of a clock optical signal.

In practice, according to a preferred embodiment, the package of the invention will have two or four connected optical fibers. In this preferred version, the package will have five metallized tracks (of the MID type) individually connected to five contacts for connection to the electrical port 3.

In one example, the connection contacts to the electrical port 3 are female contacts 32. Each contact is mounted in a housing 33 of the port 3 and is connected by its back 34 to one end of a metallized track 31. To carry out the electromagnetic shielding, each housing 33 is surrounded by a metal shielding 35 for which Figure 3 shows a view in perspective. In practice, for reasons of electrical insulation, a MID type metallization of the package will be used with two passes in this case. Figure 3 gives a view, for a tube surrounding the housing 33, of the metallization 35 that shields the housing. The remainder of the electrical port 3 is then molded over these tubes. The shielding metallizations are furthermore connected to tracks of the package connected to the ground.

Figure 2b provides a view, in order to give an idea of the size of the connector, of the dimensions in millimeters of the electrical port 3 proposed. This electrical port 3 has two ground contacts 36 and 37 at a distance of 10.5 millimeters from each other. The ground contacts 36 and 37 are connected to the shielding 35 of the pads as well as to a shielding 38 of the cavity 29. The shielding 38 is itself connected by a pad 39 and by a metallized connection 40 to a pad 41 of the integrated circuit 4 and to the shielding of the lid. In this embodiment, the distance between the consecutive contacts 32 of the electrical port 3 is 2 millimeters. In this preferred embodiment, the thickness 42 of the package including its lid 26 is about 1.95 millimeters.

Figure 4 shows a preferred exemplary view of the direct transfer of laser diodes on the integrated circuit 2. In a first step, laser diodes are laid out on a gallium arsenide substrate 43. Preferably, these diodes are Vcsel (vertical cavity solid emitting laser) type diodes. Laser diodes manufactured according to this technology have the advantage of distributing their radiation not in only one direction but in a cone 44 whose aperture is in the range of six to twelve degrees, permitting a tolerance for the positioning of the terminations of the optical fibers facing this light source and creating favorable conditions for the insertion of the optical signal into an optical fiber. As a variant, the terminations of the optical fibers are polished and may have a spherical shape so as to take account of a misalignment of the orientation of this optical fiber termination with respect to the direction of emission of the laser diode. In the preferred solution of the invention, the termination face of

the optical fibers presented by the connector 16 will be slightly inclined to prevent reflections by this face towards the laser diode and the fiber itself. Indeed, preferably the laser diode, especially when it is of the GaAs type, will be a reversible diode, namely a diode capable of working both in emission and in detection. Otherwise, for the detection, PIN diodes will be used mounted in the same way on the circuit 4. Or again the PIN diodes can be directly made by epitaxy on the circuit 4.

The diode elements can be manufactured on GaAs plates in batches and very close to one another. Thus, a plate may comprise several thousands of diodes. These diodes may be mounted on the silicon chip either individually with standard transfer machines or automatically by using a direct assembling technology. This technology has the advantage of mounting only tested diodes, reducing the complexity of the electrical connection of the diodes and achieving major savings with respect to the manufacturing method. By acting in this way and furthermore limiting the number of connectable optical fibers, a structure of the optical port is obtained that is low cost and furthermore compatible with commercially available optical connectors 16.

In one exemple, from the substrate 43, the diode elements are deposited on an intermediate support, for example a glass plate 45. The laser diodes are deposited on this glass plate with a spacing 46 equal to the spacing 21 referred to here above. If need be, the glass plate 46 exists from the very time when the laser diodes are laid out in the overlaid substrate 43. Then the substrate can be etched to allow only the diodes to remain. Then this glass plate is turned over and presented so that it faces an integrated circuit 4 formed on a silicon substrate. This integrated circuit has a substrate layer 47 and an interconnection layer 48. For the mounting of the diodes 8 on the integrated circuit 4, it can be planned to transfer them either before the interconnection phase 48 or after it. In this later case, the diodes should be connected by links between their pads 13 and pads 14 of the integrated circuit 4. The transfer is done by subjecting the glass plate 45 to laser insolation 49. The laser insolation which is a flash may be general or selective. The diodes 8 subjected to his flash get loosened and are move on to the integrated circuit 4. They are then presented on the integrated circuit 4 with a distance 50 between them equal to the distance 46 that separated

them on the glass plate 45. By acting in this way and furthermore limiting the number of connectable optical fibers, a structure of the optical port is obtained that is low cost and furthermore compatible with commercially available optical connectors 16.

5 In one example, the optical connectors 16 are formed by two jaws 51 and 52 having V-shaped grooves capable of receiving and positioning optical fibers with a precision better than one micrometer. There are ferrules in which the positioning of the fibers is achieved not by Vees but by holes made in a plastic block. The use of laser diodes whose size is in the range of
10 10 micrometers, coupled with multimode fibers with a core size of 62 micrometers, makes it possible to envisage the positioning of the fiber with a precision of 10 micrometers, which is quite sufficient. Thus, the connector 16 could be replaced by a plastic positioning part that is more economical to make.

15 The technique of directly transferring laser diodes on the integrated circuit 2 makes it possible to envisage voltage levels limited to 1.5 volts instead of the 5 volts generally encountered in the prior art when the laser diodes are individually packaged and brought to a printed circuit. A technology of this kind will therefore go together with a reduction in
20 consumption. In practice, a consumption level of about 1 milliwatt per diode is achieved instead of the 10 milliwatts consumed in the prior art. Thus, it is fairly easy to bring the diodes closer together and especially to hold at least two of them on one and the same substrate 4 without any risk of any major drift in the operating characteristics of the diodes of the integrated circuit 4
25 through an excessive rise in their temperature.

Furthermore, the limiting of the heating is accompanied by a smaller drift in the laser diodes. This, in particular, leads to a simplification of the driving circuits 6 (which furthermore reduces the thermal dissipation).

The approach presented in the invention has the advantage of being
30 totally industrial and of limiting manual operations, by reducing them to simple handling operations in preventing intervention especially entailing the use of binoculars. It is well suited to batch production. Thus, the invention achieves the desired result of obtaining an optoelectronic connection module whose cost price, at least for the connection of two optical fibers, is
35 proportionally smaller than the cost of making a connector for a large number

13

of optical fibers. The process of the batch transfer of the laser diodes to one or more integrated circuits 4 makes it possible to reduce the cost of the optoelectronic component.

5 As a variant, the guidance part 18 is an integral part of the optoelectronic connector. This part 18 is then in the package in a position such that the mirror 19 is located above the laser diodes 8. It is also possible to consider doing without the inclined face 19 by making optical fiber terminations that are curved so that their section is presented before the emission cone of the diodes 8. In another variant, the integrated circuit 4 is
10 shown vertically in the package 1 so that the radiation of the diodes 8 is oriented to be facing the direction in which the connector 16 is introduced into the port 2. As an alternative, the part 18 has jaws such as 51 and 52 to receive ferrules of optical fibers.

CLAIMS

1. Optoelectronic connector comprising a package (1), an optical port (2), an electrical port (3), an optoelectronic circuit positioned in this package and connected to these two ports, the optoelectronic circuit comprising a bare control (5_7) and emission-detection (8) integrated circuit chip, an internal wall (29) of the package being provided with metallized connections (11), pads (10) of this integrated circuit being connected (12) directly to the metallized connections, characterized in that it comprises laser diodes (8) being transferred on the integrated circuit, this connector constituting a basic unit link.

2. Connector according to claim 1, characterized in that the laser diodes (8) are transferred (45) on the integrated circuit with a space (50) between these diodes equal to a space (21) between optical fiber terminations in the optical port.

3. Connector according to one of the claims 1 to 2, characterized in that the package is an MID type package with connection metallizations deposited in a cavity of this package, contact armorings of the electrical port of this connector being formed by one of these metallizations.

4. Connector according to claim 3, characterized in that the MID type package is made by means of a method with metallizations in two passes.

5. Connector according to one of the claims 3 to 4, characterized in that the package is connected to the integrated circuit by BGA type connections, wire bonding or anisotropic film technology.

6. Connector according to one of the claims 3 to 5, characterized in that the shielding of the package is of an MID type.

7. Connector according to one of the claims 1 to 6, characterized in that pads (10) of the integrated circuit are connected (12) directly to the metallized connections.

8. Connector according to one of the claims 1 to 7, characterized in that the laser diodes are Vcsel diodes, preferably of the GaAs type.

9. Connector according to one of the claims 1 to 8, characterized in that the optical port comprises an inclined mirror (19), preferably inclined at 45°.

10. Connector according to one of the claims 1 to 9, characterized in

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that the optical port comprises a part (18) for positioning optical fiber terminations, this part abutting (23) a cant (24) of the integrated circuit.

11. Connector according to one of the claims 1 to 10, characterized in that the optical port comprises a limited access with two optical channels and in that the electrical port comprises contacts for electrical signals and contacts for a ground signal.

12. Connector according to one of the claims 1 to 11, characterized in that the package is a module and comprises means (27, 28) to be stacked on another package.

10 13. Connector according to one of the claims 1 to 12, characterized in that pads of the laser diodes are connected by connection wires directly to pads of the integrated circuit.

14. Connector according to one of the claims 1 to 13, characterized in that the optoelectronic circuit comprises means to carry out a conversion of the signals available at the optical port into signals available at the electrical port and/or vice versa.

Table 1. Demographic characteristics of the study population	
Age (mean ± SD)	65.2 ± 10.5
Gender (male/female)	112/108
Education (years)	12.5 ± 2.1
Marital status (married/divorced/widowed)	150/45/10
Occupation (retired/working)	160/50
Health status (good/fair/poor)	150/40/10
Comorbidities (hypertension/diabetes/cholesterol)	120/80/60
Medication (antidepressants/antipsychotics)	100/40
Alcohol consumption (yes/no)	30/180
Smoking status (smoker/non-smoker)	50/170
Family size (mean ± SD)	3.2 ± 1.5
Income (monthly, \$)	1,200 ± 300
Living arrangement (alone/with family/with friends)	40/140/20
Religious affiliation (Christian/Jewish/Muslim)	150/10/10
Duration of illness (years)	5.2 ± 3.1
Previous hospitalizations (yes/no)	120/80
Current symptoms (depression/anxiety)	150/100
Functional status (independent/dependent)	140/60
Social support (strong/weak)	100/100
Stress levels (high/low)	80/120
Life satisfaction (satisfied/dissatisfied)	120/80
Quality of life (high/low)	100/100
Overall health (good/fair/poor)	150/40/10
Physical health (good/fair/poor)	140/50/10
Mental health (good/fair/poor)	130/60/10
Social health (good/fair/poor)	120/70/10
Emotional health (good/fair/poor)	110/80/10
Financial health (good/fair/poor)	100/90/10
Environmental health (good/fair/poor)	90/100/10
Overall well-being (good/fair/poor)	150/40/10
Life expectancy (years)	15.2 ± 2.1
Quality of life index (0-100)	65.2 ± 10.5
Functional status index (0-100)	75.2 ± 10.5
Social support index (0-100)	85.2 ± 10.5
Stress levels index (0-100)	95.2 ± 10.5
Life satisfaction index (0-100)	105.2 ± 10.5
Quality of life index (0-100)	115.2 ± 10.5
Overall health index (0-100)	125.2 ± 10.5
Physical health index (0-100)	135.2 ± 10.5
Mental health index (0-100)	145.2 ± 10.5
Social health index (0-100)	155.2 ± 10.5
Emotional health index (0-100)	165.2 ± 10.5
Financial health index (0-100)	175.2 ± 10.5
Environmental health index (0-100)	185.2 ± 10.5
Overall well-being index (0-100)	195.2 ± 10.5
Life expectancy index (0-100)	205.2 ± 10.5
Quality of life index (0-100)	215.2 ± 10.5
Functional status index (0-100)	225.2 ± 10.5
Social support index (0-100)	235.2 ± 10.5
Stress levels index (0-100)	245.2 ± 10.5
Life satisfaction index (0-100)	255.2 ± 10.5
Quality of life index (0-100)	265.2 ± 10.5
Overall health index (0-100)	275.2 ± 10.5
Physical health index (0-100)	285.2 ± 10.5
Mental health index (0-100)	295.2 ± 10.5
Social health index (0-100)	305.2 ± 10.5
Emotional health index (0-100)	315.2 ± 10.5
Financial health index (0-100)	325.2 ± 10.5
Environmental health index (0-100)	335.2 ± 10.5
Overall well-being index (0-100)	345.2 ± 10.5
Life expectancy index (0-100)	355.2 ± 10.5
Quality of life index (0-100)	365.2 ± 10.5
Functional status index (0-100)	375.2 ± 10.5
Social support index (0-100)	385.2 ± 10.5
Stress levels index (0-100)	395.2 ± 10.5
Life satisfaction index (0-100)	405.2 ± 10.5
Quality of life index (0-100)	415.2 ± 10.5
Overall health index (0-100)	425.2 ± 10.5
Physical health index (0-100)	435.2 ± 10.5
Mental health index (0-100)	445.2 ± 10.5
Social health index (0-100)	455.2 ± 10.5
Emotional health index (0-100)	465.2 ± 10.5
Financial health index (0-100)	475.2 ± 10.5
Environmental health index (0-100)	485.2 ± 10.5
Overall well-being index (0-100)	495.2 ± 10.5
Life expectancy index (0-100)	505.2 ± 10.5
Quality of life index (0-100)	515.2 ± 10.5
Functional status index (0-100)	525.2 ± 10.5
Social support index (0-100)	535.2 ± 10.5
Stress levels index (0-100)	545.2 ± 10.5
Life satisfaction index (0-100)	555.2 ± 10.5
Quality of life index (0-100)	565.2 ± 10.5
Overall health index (0-100)	575.2 ± 10.5
Physical health index (0-100)	585.2 ± 10.5
Mental health index (0-100)	595.2 ± 10.5
Social health index (0-100)	605.2 ± 10.5
Emotional health index (0-100)	615.2 ± 10.5
Financial health index (0-100)	625.2 ± 10.5
Environmental health index (0-100)	635.2 ± 10.5
Overall well-being index (0-100)	645.2 ± 10.5
Life expectancy index (0-100)	655.2 ± 10.5
Quality of life index (0-100)	665.2 ± 10.5
Functional status index (0-100)	675.2 ± 10.5
Social support index (0-100)	685.2 ± 10.5
Stress levels index (0-100)	695.2 ± 10.5
Life satisfaction index (0-100)	705.2 ± 10.5
Quality of life index (0-100)	715.2 ± 10.5
Overall health index (0-100)	725.2 ± 10.5
Physical health index (0-100)	735.2 ± 10.5
Mental health index (0-100)	745.2 ± 10.5
Social health index (0-100)	755.2 ± 10.5
Emotional health index (0-100)	765.2 ± 10.5
Financial health index (0-100)	775.2 ± 10.5
Environmental health index (0-100)	785.2 ± 10.5
Overall well-being index (0-100)	795.2 ± 10.5
Life expectancy index (0-100)	805.2 ± 10.5
Quality of life index (0-100)	815.2 ± 10.5

1/2

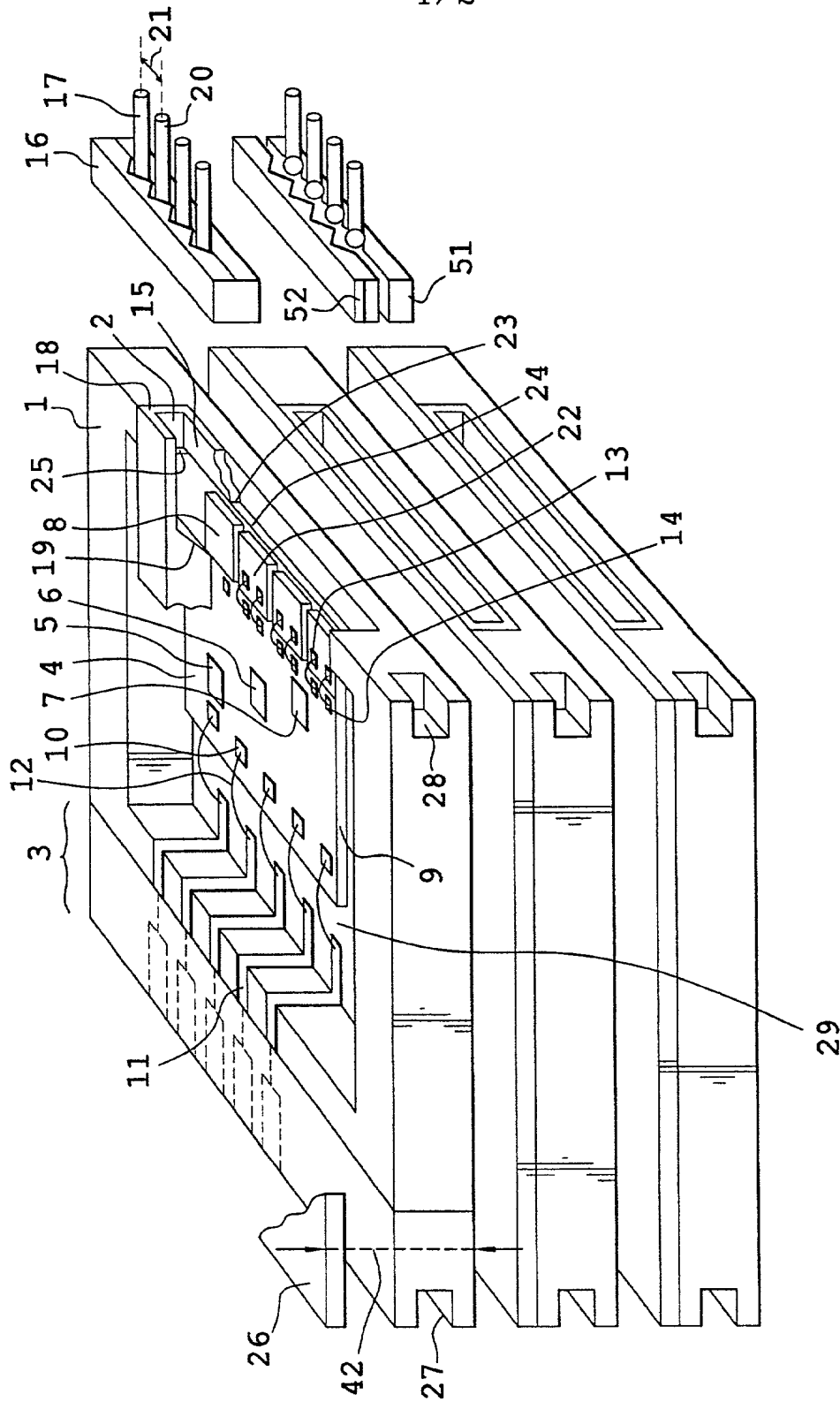


Fig. 1

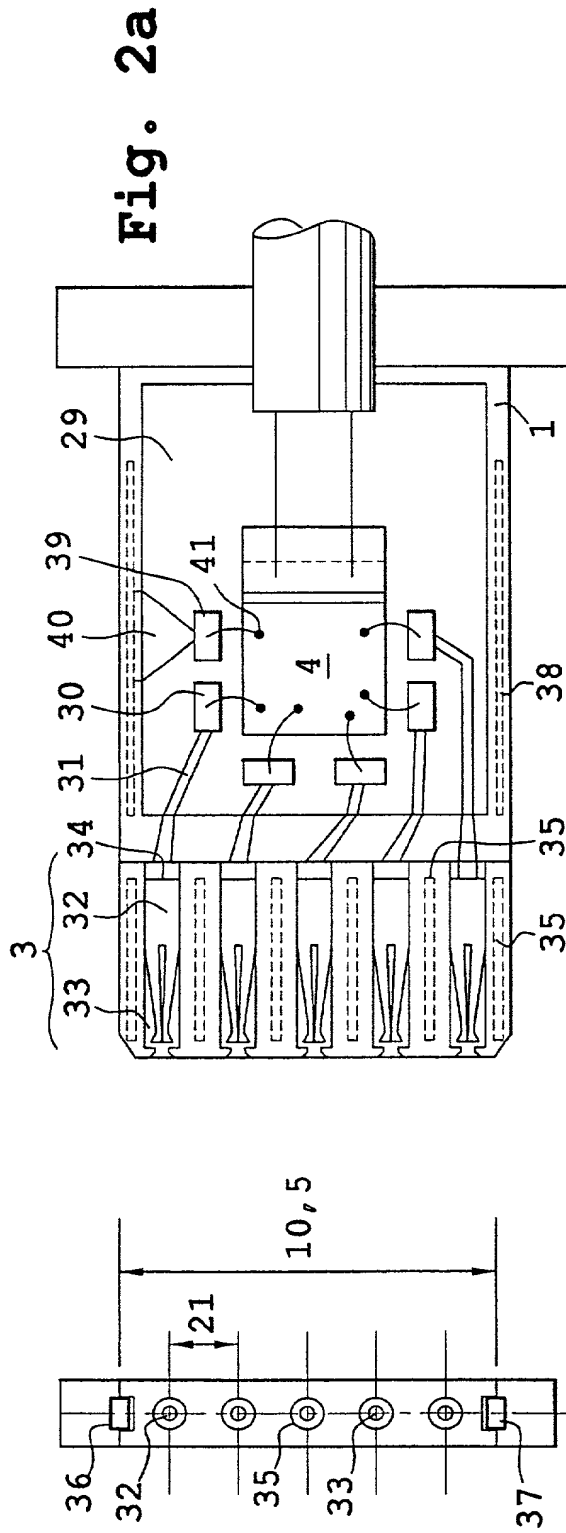


Fig. 2b

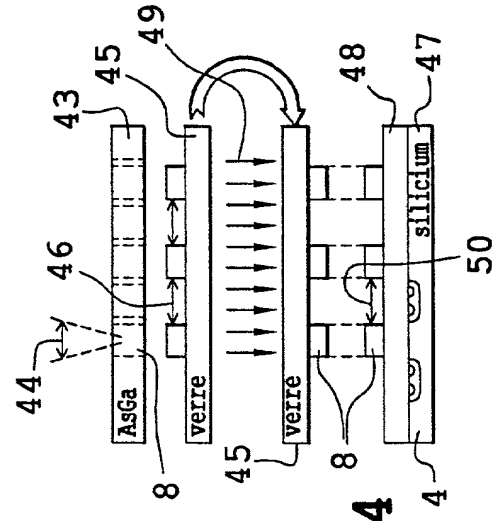


Fig. 4

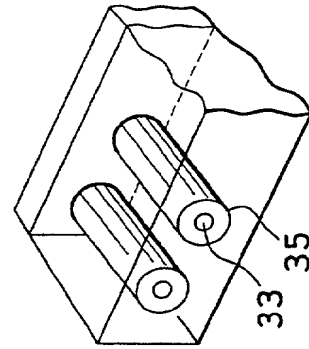


Fig. 3

DECLARATION AND POWER OF ATTORNEY FOR PATENT APPLICATION

English Language Declaration

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name,

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

Title: MODULAR OPTOELECTRONIC CONNECTOR

the specification of which

(check one)

☐

is attached hereto.

X

was filed on as United States Application No.09/936,951 or PCT
International Application Number PCT/EP00/02747 filed on March 2, 2000
and was amended on (if applicable)

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose to the United States Patent and Trademark Office all information known to me to be material to patentability as defined in Title 37, Code of Federal Regulations, Section 1.56.

I hereby claim foreign priority benefits under Title 35, United States Code, Section 119(a)-(d) or Section 365(b) of any foreign application(s) for patent or inventor's certificate, or Section 365(a) of any PCT International Application which designated at least one country other than the United States, listed below and have also identified below, by checking the box, any foreign application for patent or inventor's certificate or PCT International application having a filing date before that of the application on which priority is claimed.

Prior Foreign Application(s)

(Number)	(Country)	(Day/Month/Year Filed)	<u>Priority Not Claimed</u>
PCT/EP00/02747	PCT	2 March 2000	<input type="checkbox"/>
FR 99/03226	France	16 March 1999	<input type="checkbox"/>
FR 99/03222	France	16 March 1999	<input type="checkbox"/>
FR 99/03224	France	16 March 1999	<input type="checkbox"/>

I hereby claim the benefit under 35 U.S.C. Section 119(e) of any United States provisional application(s) listed below:

(Application Serial No.)

(Filing Date)

(Application Serial No.)

(Filing Date)

(Application Serial No.):

(Filing Date)

I hereby claim the benefit under 35 U.S.C. Section 120 of any United States application(s), or Section 365(c) of any PCT International Application designating the United States, listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States or PCT International Application in the manner provided by the first paragraph of 35 U.S.C. Section 112, I acknowledge the duty to disclose to the United States Patent and Trademark Office all information known to me to be material to patentability as defined in Title 37, C.F.R., Section 1.56 which became available between the filing date of the prior application and the national or PCT International filing date of this application.

(Application Serial No.)

(Filing Date)

(Status)
(patented, pending, abandoned)

(Application Serial No.)

(Filing Date)

(Status)
(patented, pending, abandoned)

(Application Serial No.)

(Filing Date)

(Status)
(patented, pending, abandoned)

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

POWER OF ATTORNEY: As a named inventor, I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and transact all business in the Patent and Trademark Office connected therewith. (list name and registration number)

All attorneys listed under Customer No.: 2512

Send Correspondence to:

Customer No.: 2512

Direct Telephone Calls to: (name and telephone number)
Clarence A. Green, Reg. No.: 24,622 (203) 259-1800

Full name of sole or first inventor

Bernard ROBERT

Sole or first inventor's signature.

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Citizenship:

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Post Office Address.

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Second inventor's signature: *EL MOSTAFA ZINDINE*

DATE

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Citizenship

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Post Office Address.

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Full name of third inventor:

Bernard BRICE

Third Inventor's signature:

Bernard Brice

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Citizenship:

French

Post Office Address:

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Full name of fourth inventor:

Fourth inventor's signature:

DATE

Residence address:

Citizenship

Post Office Address:

Full name of fifth inventor:

Fifth inventor's signature:

DATE

Residence address:

Citizenship

Post Office Address:

☐

Check here if additional pages are attached

Number of added pages

Page 4 of 4

Docket No.: 704-010563-US(PAR)

DECLARATION AND POWER OF ATTORNEY FOR PATENT APPLICATION

English Language Declaration

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

Title: MODULAR OPTOELECTRONIC CONNECTOR

the specification of which

(check one)

☐ is attached hereto.

X was filed on as United States Application No.09/936,951 or PCT
International Application Number PCT/EP00/02747 filed on March 2, 2000
and was amended on (if applicable)

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

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I hereby claim foreign priority benefits under Title 35, United States Code, Section 119(a)-(d) or Section 365(b) of any foreign application(s) for patent or inventor's certificate, or Section 365(a) of any PCT International Application which designated at least one country other than the United States, listed below and have also identified below, by checking the box, any foreign application for patent or inventor's certificate or PCT International application having a filing date before that of the application on which priority is claimed.

Prior Foreign Application(s)

(Number)	(Country)	(Day/Month/Year Filed)	<u>Priority Not Claimed</u>
PCT/EP00/02747	PCT	2 March 2000	<input type="checkbox"/>
FR 99/03226	France	16 March 1999	<input type="checkbox"/>
FR 99/03222	France	16 March 1999	<input type="checkbox"/>
FR 99/03224	France	16 March 1999	<input type="checkbox"/>

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(Application Serial No.)

(Filing Date)

(Application Serial No.)

(Filing Date)

(Application Serial No.)

(Filing Date)

I hereby claim the benefit under 35 U.S.C. Section 120 of any United States application(s), or Section 365(c) of any PCT International Application designating the United States, listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States or PCT International Application in the manner provided by the first paragraph of 35 U.S.C. Section 112, I acknowledge the duty to disclose to the United States Patent and Trademark Office all information known to me to be material to patentability as defined in Title 37, C.F.R., Section 1.56 which became available between the filing date of the prior application and the national or PCT International filing date of this application:

(Application Serial No.)

(Filing Date)

(Status)
(patented, pending, abandoned)

(Application Serial No.)

(Filing Date)

(Status)
(patented, pending, abandoned)

(Application Serial No.)

(Filing Date)

(Status)
(patented, pending, abandoned)

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

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Clarence A. Green, Reg. No.: 24,622 (203) 259-1800

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Bernard ROBERT

Sole or first inventor's signature

Bernard Robert.

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Second inventor's signature:

EL MOSTAFA ZINDINE

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Citizenship.

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Third inventor's signature:

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French

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Fourth inventor's signature:

Bernard Robert.

DATE

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3 Rue du Gros Tilland

Citizenship:

Pontarlier.

Post Office Address:

25. 300. France.

Full name of fifth inventor:

Fifth inventor's signature:

DATE

Residence address:

Citizenship:

Post Office Address:

☐

Check here if additional pages are attached

Number of added pages: